



DCR780G42

Phase Control Thyristor

Replaces DS5829-4 DS5829-5 February 2014 (LN31341)

FEATURES

- Double Side Cooling
- High Surge Capability

APPLICATIONS

- High Power Drives
- High Voltage Power Supplies
- Static Switches

VOLTAGE RATINGS

Part and Ordering Number	Repetitive Peak Voltages V _{DRM} and V _{RRM} V	Conditions
DCR780G42 DCR780G40 DCR780G38	4200 4000 3800	$\begin{split} T_{vj} &= \text{-}40^{\circ}\text{C to 125}^{\circ}\text{C}, \\ I_{DRM} &= I_{RRM} = 100\text{mA}, \\ V_{DRM}, \ V_{RRM} \ t_p = 10\text{ms}, \\ V_{DSM} \ \& \ V_{RSM} = \\ V_{DRM} \ \& \ V_{RRM} + 100V \\ respectively \end{split}$

Lower voltage grades available.

ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

DCR780G42

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

KEY PARAMETERS

 $\begin{array}{lll} V_{DRM} & 4200V \\ I_{T(AV)} & 780A \\ I_{TSM} & 10500A \\ dV/dt^* & 1500V/\mu s \\ dI/dt & 400A/us \end{array}$

* Higher dV/dt selections available

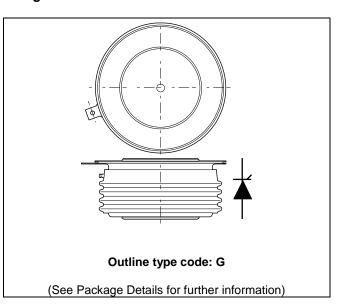


Fig. 1 Package outline

www.dynexsemi.com 1/10



CURRENT RATINGS

T_{case} = 60°C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Double Sid	de Cooled			
I _{T(AV)}	Mean on-state current	Half wave resistive load	780	Α
I _{T(RMS)}	RMS value	-	1225	Α
Ι _Τ	Continuous (direct) on-state current	-	1173	Α

SURGE RATINGS

Symbol Parameter		Test Conditions	Max.	Units
I _{TSM}	Surge (non-repetitive) on-state current	10ms half sine, T _{case} = 125°C	10.5	kA
I ² t I ² t for fusing		$V_R = 0$	0.55	MA ² s

THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
R _{th(j-c)}	Thermal resistance – junction to case	Double side cooled	DC	-	0.0268	°C/W
		Single side cooled	Anode DC	-	0.0527	°C/W
			Cathode DC	-	0.0652	°C/W
R _{th(c-h)}	Thermal resistance – case to heatsink	Clamping force 11.5kN	Double side	-	0.0072	°C/W
		(with mounting compound)	Single side	-	.0144	°C/W
T_{vj}	Virtual junction temperature	Blocking V _{DRM} / _{VRRM}		-	125	°C
T _{stg}	Storage temperature range			-55	125	°C
F _m	Clamping force			10	13	kN

www.dynexsemi.com 2/10



DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Conditio	ns	Min.	Max.	Units
I _{RRM} /I _{DRM}	Peak reverse and off-state current	At V _{RRM} /V _{DRM} , T _{case} = 125°C		-	100	mA
dV/dt	Max. linear rate of rise of off-state voltage	To 67% V_{DRM} , $T_j = 125$ °C, ga	ate open	-	1500	V/µs
dl/dt	Rate of rise of on-state current	From 67% V _{DRM} to 2x I _{T(AV)}	Repetitive 50Hz	-	200	A/µs
		Gate source 30V, 10Ω,	Non-repetitive	-	400	A/µs
		$t_r < 0.5 \mu s, T_j = 125$ °C				
$V_{T(TO)}$	Threshold voltage – Low level	100A to 500A at T _{case} = 125°	С	-	.87	V
	Threshold voltage – High level	500A to 3000A at T _{case} = 125	5°C	-	1.053	V
r _T	On-state slope resistance – Low level	100A to 500A at T _{case} = 125°C		-	1.2244	mΩ
	On-state slope resistance – High level	500A to 3000A at T _{case} = 125°C		-	0.8443	mΩ
t _{gd}	Delay time	$V_D = 67\% V_{DRM}$, gate source 30V, 10Ω		TBD	TBD	μs
		$t_r = 0.5 \mu s, T_j = 25^{\circ}C$				
tq	Turn-off time	$T_j = 125$ °C, $V_R = 200$ V, $dI/dt = 5$ A/ μ s,		300	600	μs
		dV _{DR} /dt = 20V/μs linear				
$Q_{\mathbb{S}}$	Stored charge	$I_T = 2000A$, $T_j = 125$ °C, $dI/dt = 5A/\mu s$,		1100	2200	μC
IL	Latching current	$T_j = 25^{\circ}C, V_D = 5V$		-	3	А
I _H	Holding current	$T_j = 25^{\circ}\text{C}, R_{G-K} = \infty, I_{TM} = 50^{\circ}$	0A, I _T = 5A	-	300	mA

www.dynexsemi.com 3/10



GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol Parameter		Test Conditions	Max.	Units
V_{GT}	Gate trigger voltage	V _{DRM} = 5V, T _{case} = 25°C	1.5	V
V_{GD}	Gate non-trigger voltage	At 50% V _{DRM} , T _{case} = 125°C	0.4	V
I _{GT}	Gate trigger current	V _{DRM} = 5V, T _{case} = 25°C	350	mA
I _{GD}	Gate non-trigger current	At 50% V _{DRM} , T _{case} = 125°C	10	mA

CURVES

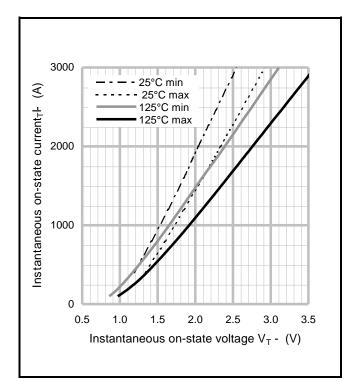


Fig.2 Maximum & minimum on-state characteristics

these values are valid for T_j = 125°C for I_T 50A to 3000A

www.dynexsemi.com 4/10



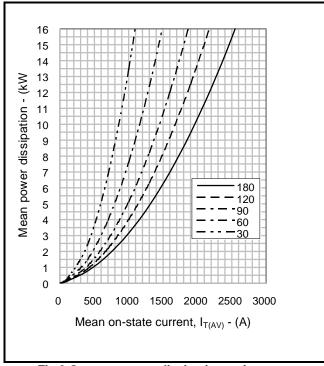
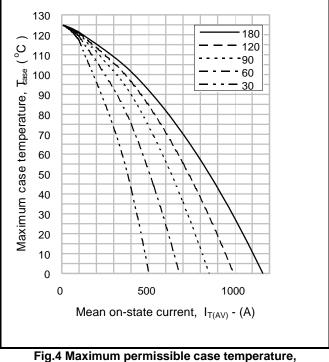


Fig.3 On-state power dissipation - sine wave



double side cooled – sine wave

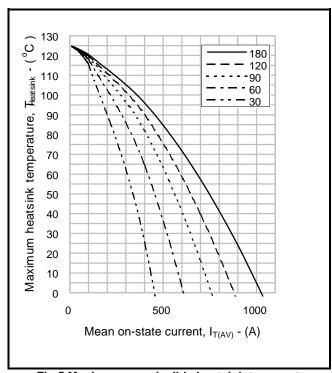


Fig.5 Maximum permissible heatsink temperature, double side cooled – sine wave

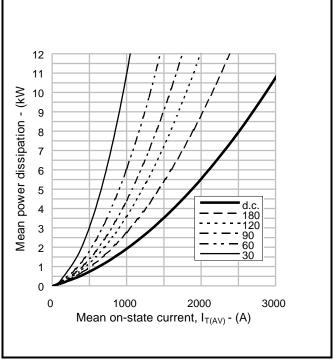


Fig.6 On-state power dissipation - rectangular wave

www.dynexsemi.com 5/10



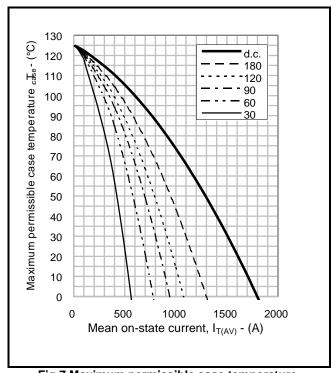


Fig.7 Maximum permissible case temperature, double side cooled – rectangular wave

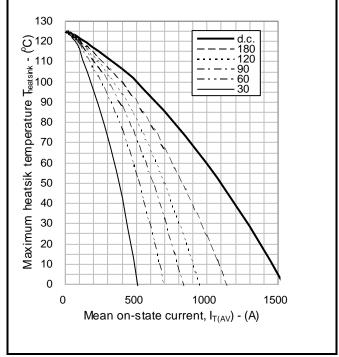
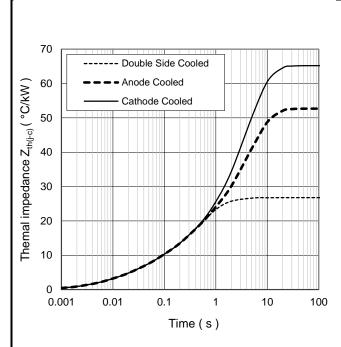


Fig.8 Maximum permissible heatsink temperature, double side cooled – rectangular wave



		1	2	3	4
Double side cooled	R _i (°C/kW)	2.2995	5.4226	16.9074	2.1488
	T _i (s)	0.0066401	0.0457025	0.4962482	1.8248
Anode side cooled	R _i (°C/kW)	2.3214	5.2661	10.2686	34.8031
	T _i (s)	0.0066948	0.045528	0.3484209	4.582
Cathode side cooled	R _i (°C/kW)	2.4895	5.9105	7.4256	49.3432
	T; (s)	0.0070404	0.052895	0.3933903	4 2295

$$Z_{th} = \sum_{i=1}^{i=4} [R_i \times (1 - \exp(-T/T_i))]$$

 $\Delta R_{\text{th(j-c)}}$ Conduction

Tables show the increments of thermal resistance $R_{\text{th}(j\text{-}c)}$ when the device operates at conduction angles other than d.c.

			Α				
	ΔZ_{th} ((z)			Ī		
θ°	sine.	rect.		θ°	Ι		
180	4.15	2.72		180	I		
120	4.90	4.02		120	I		
90	5.74	4.79		90	I		
60	6.53	5.65		60	I		
30	7.16	6.64		30	Ī		
4.5	7.40	7.40		4.5	Г		

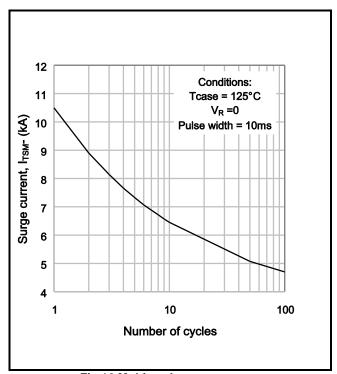
		Anode Side Cooling					
		ΔZ_{th} (z)					
	θ°	sine.	rect.				
	180	4.15	2.72				
	120	4.89	4.02				
	90	5.73	4.78				
	60	6.52	5.65				
	30	7.15	6.62				

Ca	Cathode Sided Cooling				
	$\Delta Z_{th}(z)$				
θ°	sine.	rect.			
180	4.13	2.71			
120	4.87	4.00			
90	5.69	4.76			
60	6.46	5.60			
30	7.07	6.56			
15	7 36	7.09			

Fig.9 Maximum (limit) transient thermal impedance - junction to case (°C/kW)

www.dynexsemi.com 6/10





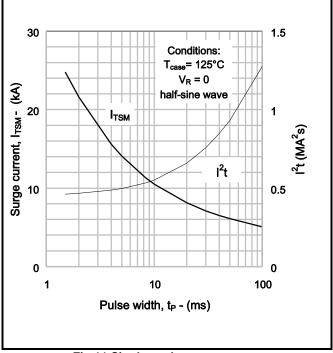
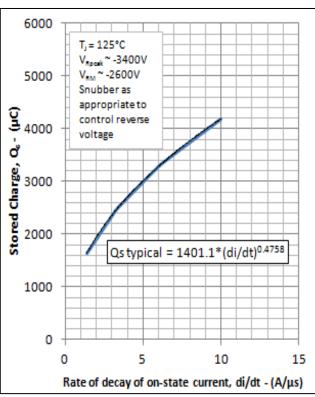


Fig.10 Multi-cycle surge current

Fig.11 Single-cycle surge current



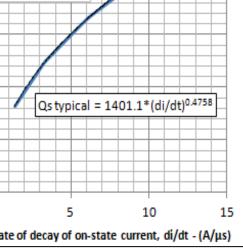


Fig.12 Stored Charge vs di/dt

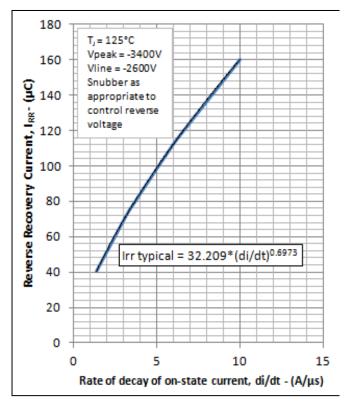


Fig.13 Reverse Recorvery Current vs di/dt

7/10 www.dynexsemi.com



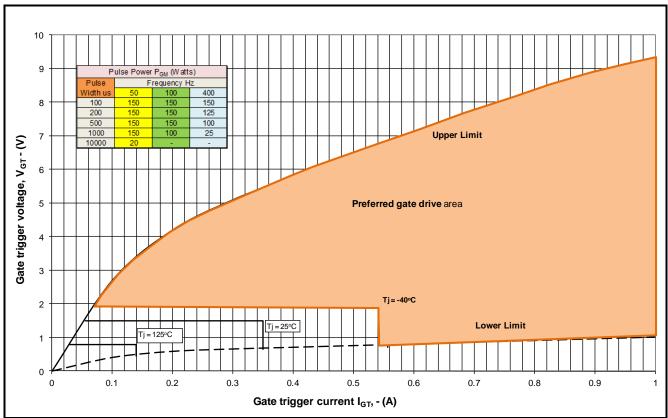


Fig14 Gate Characteristics

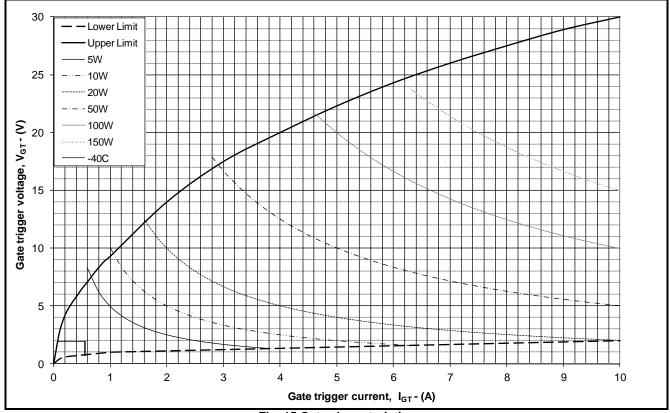


Fig. 15 Gate characteristics

www.dynexsemi.com 8/10



PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

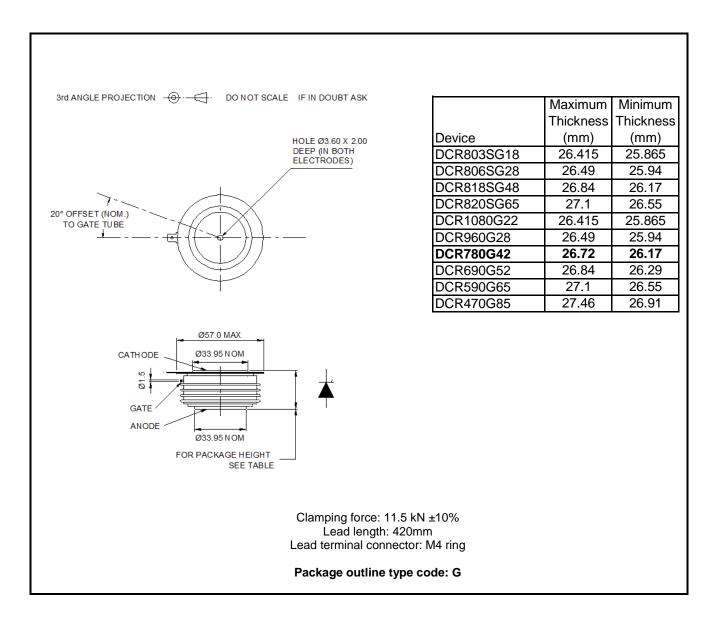


Fig.16 Package outline

www.dynexsemi.com 9/10



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No actual design work on the product has been started.

Preliminary Information:The product design is complete and final characterisation for volume production is in progress. The datasheet represents the product as it is now understood but details may change.

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www.dynexsemi.com 10/10